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FDV304P Digital FET, P-Channel

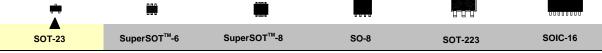
General Description

This P-Channel enhancement mode field effect transistors is produced using ON Semiconductor's proprietary, high cell density, DMOS technology. This very high density process is tailored to minimize on-state resistance at low gate drive conditions. This device is designed especially for application in battery power applications such as notebook computers and cellular phones. This device has excellent on-state resistance even at gate drive voltages as low as 2.5 volts.

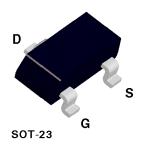
Features

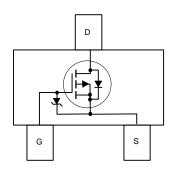
 $\begin{tabular}{llll} & -25~V, -0.46~A~continuous, -1.5~A~Peak. \\ & R_{DS(ON)} = 1.1~\Omega~@~V_{GS} = -4.5~V \\ & R_{DS(ON)} = 1.5~\Omega~@~V_{GS} = -2.7~V. \\ \end{tabular}$

- Very low level gate drive requirements allowing direct operation in 3V circuits. V_{GS(th)} < 1.5V.
- Gate-Source Zener for ESD ruggedness. >6kV Human Body Model
- Compact industry standard SOT-23 surface mount package.



Mark:304





Absolute Maximum Ratings $T_A = 25^{\circ}C$ unless other wise noted

Symbol	Parameter	FDV304P	Units
V _{DSS}	Drain-Source Voltage	-25	V
V_{GSS}	Gate-Source Voltage	-8	V
I _D	Drain Current - Continuous	-0.46	А
	- Pulsed	-1.5	
P _D	Maximum Power Dissipation	0.35	W
T_J , T_{STG}	Operating and Storage Temperature Range	-55 to 150	°C
ESD	Electrostatic Discharge Rating MIL-STD-883D Human Body Model (100pf / 1500 Ohm)	6.0	kV
THERMA	L CHARACTERISTICS		<u>.</u>
R _{eJA}	Thermal Resistance, Junction-to-Ambient	357	°C/W

Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHAR	ACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$		-25			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	I _D = -250 μA, Referenced to 25 °C			-22		mV /°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -20 \text{ V}, \ V_{GS} = 0 \text{ V}$				-1	μA
			$T_J = 55^{\circ}C$			-10	μA
I _{GSS}	Gate - Body Leakage Current	$V_{GS} = -8 \text{ V}, \ V_{DS} = 0 \text{ V}$				-100	nA
	CTERISTICS (Note)	1 33		ı		ı	
$\Delta V_{GS(th)}/\Delta T_{J}$	Gate Threshold Voltage Temp. Coefficient	I _D = -250 μA, Referenced to 25 °C			2.1		mV /°C
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$		-0.65	-0.86	-1.5	V
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = -2.7 \text{ V}, I_{D} = -0.25 \text{ A}$			1.22	1.5	.5 Ω
		$V_{GS} = -4.5 \text{ V}, I_{D} = -0.5 \text{ A}$			0.87	1.1	
			T _J =125°C		1.21	2	
D(ON)	On-State Drain Current	$V_{GS} = -2.7 \text{ V}, \ V_{DS} = -5 \text{ V}$	•	-0.5			Α
		$V_{GS} = -4.5 \text{ V}, \ V_{DS} = -5 \text{ V}$		-1			
g _{FS}	Forward Transconductance	$V_{DS} = -5 \text{ V}, I_{D} = -0.5 \text{ A}$			0.8		S
DYNAMIC C	CHARACTERISTICS						
C _{iss}	Input Capacitance	$V_{DS} = -10 \text{ V}, \ V_{GS} = 0 \text{ V},$ f = 1.0 MHz			63		pF
Coss	Output Capacitance				34		pF
C _{rss}	Reverse Transfer Capacitance				10		pF
SWITCHING	CHARACTERISTICS (Note)						
D(on)	Turn - On Delay Time	$V_{DD} = -6 \text{ V}, \ I_{D} = -0.5 \text{ A},$ $V_{GS} = -4.5 \text{ V}, \ R_{GEN} = 50 \Omega$			7	20	ns
r	Turn - On Rise Time				8	20	ns
D(off)	Turn - Off Delay Time				55	110	ns
f	Turn - Off Fall Time				35	70	ns
Q_g	Total Gate Charge	$V_{DS} = -5 \text{ V}, \ I_{D} = -0.25 \text{ A}, \ V_{GS} = -4.5 \text{ V}$			1.1	1.5	nC
Q_{gs}	Gate-Source Charge				0.32		nC
Q_{gd}	Gate-Drain Charge				0.25		nC
DRAIN-SOU	RCE DIODE CHARACTERISTICS AND MAX	IMUM RATINGS					
s	Maximum Continuous Drain-Source Diode Forward Current				-0.5	Α	
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -0.5 \text{ A}$ (Note)			-0.89	-1.2	V

Note: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2.0%.

Typical Electrical Characteristics

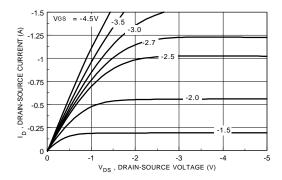


Figure 1. On-Region Characteristics.

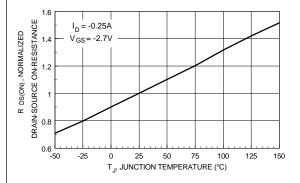


Figure 3. On-Resistance Variation with Temperature.

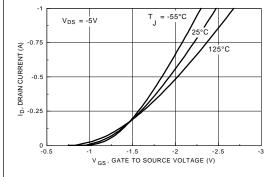


Figure 5. Transfer Characteristics.

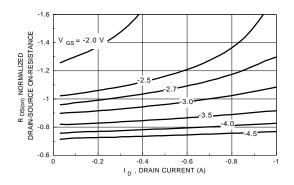


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

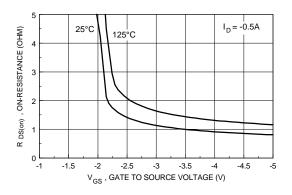


Figure 4. On Resistance Variation with Gate-To- Source Voltage.

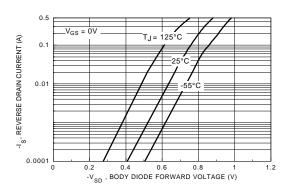


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Electrical And Thermal Characteristics

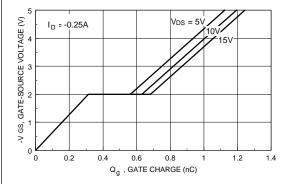
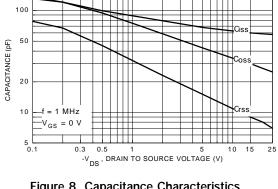


Figure 7. Gate Charge Characteristics.



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Figure 8. Capacitance Characteristics.

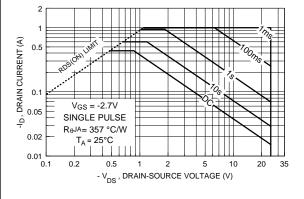


Figure 9. Maximum Safe Operating Area.

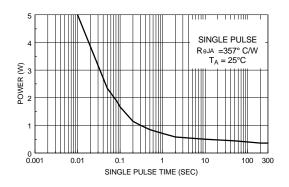


Figure 10. Single Pulse Maximum Power Dissipation.

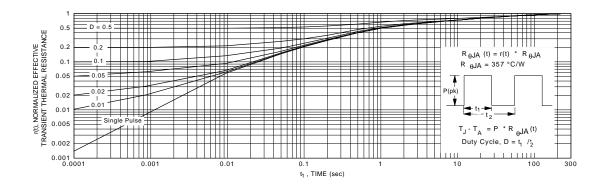


Figure 11. Transient Thermal Response Curve.

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